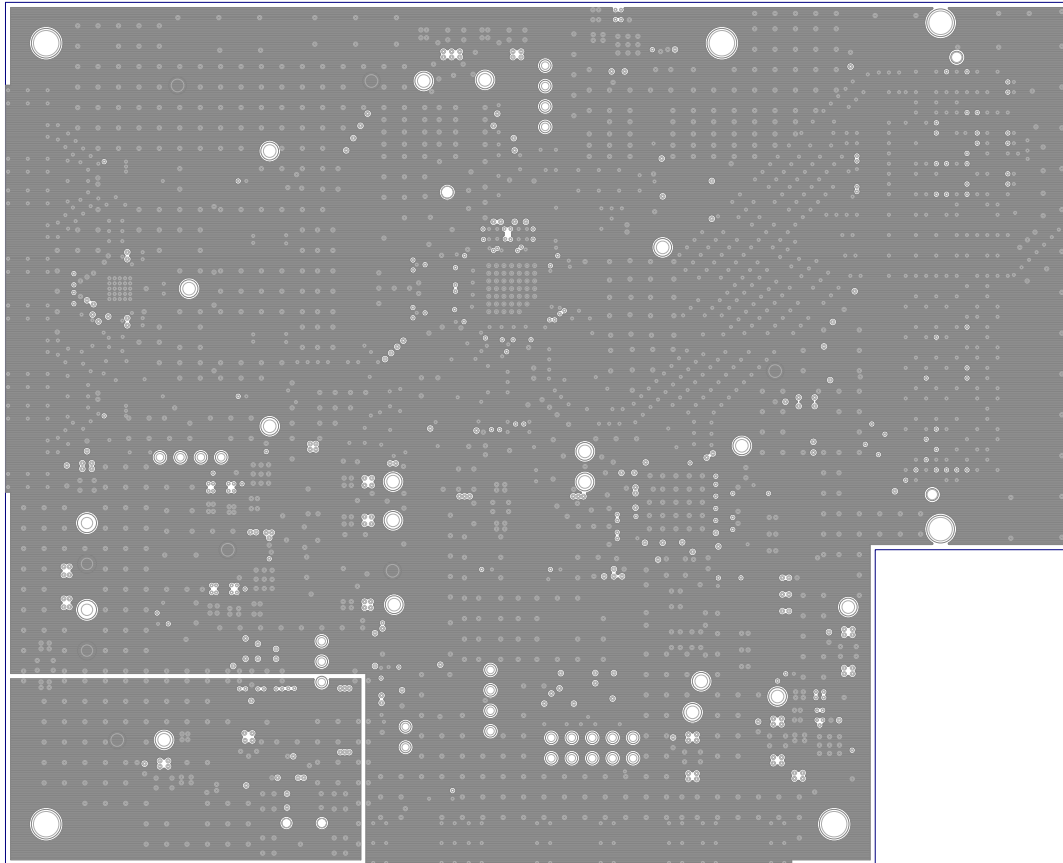
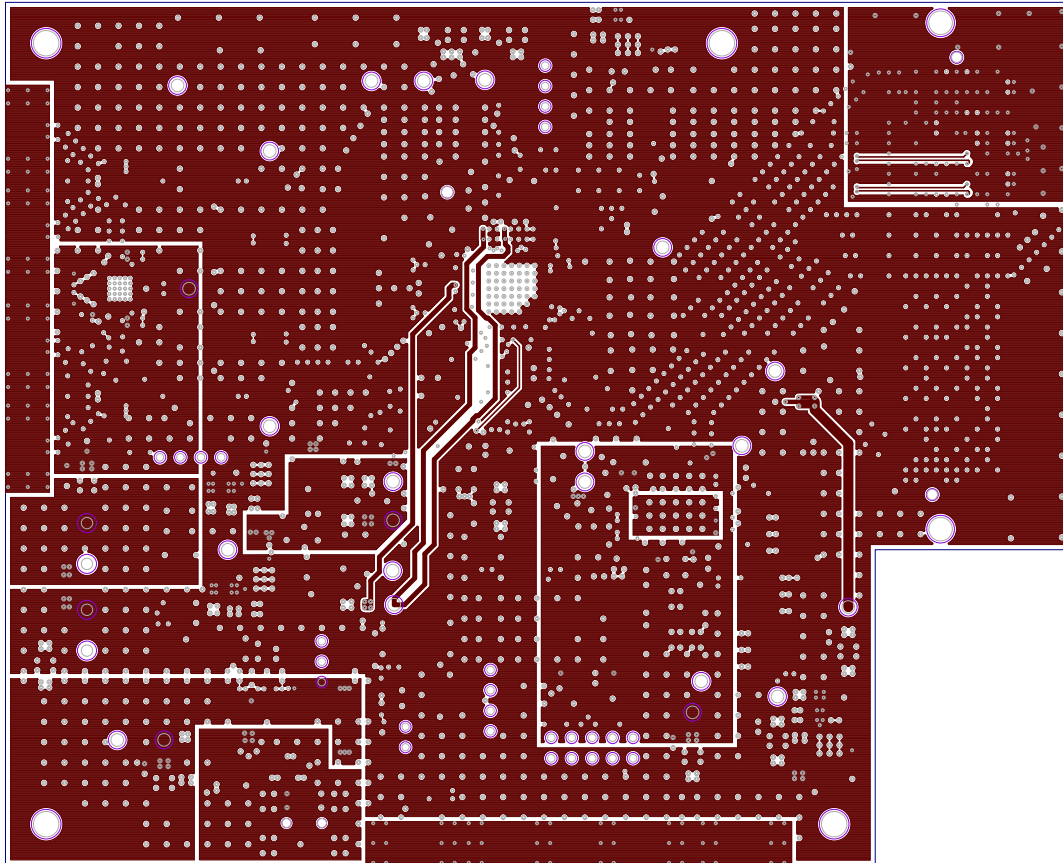


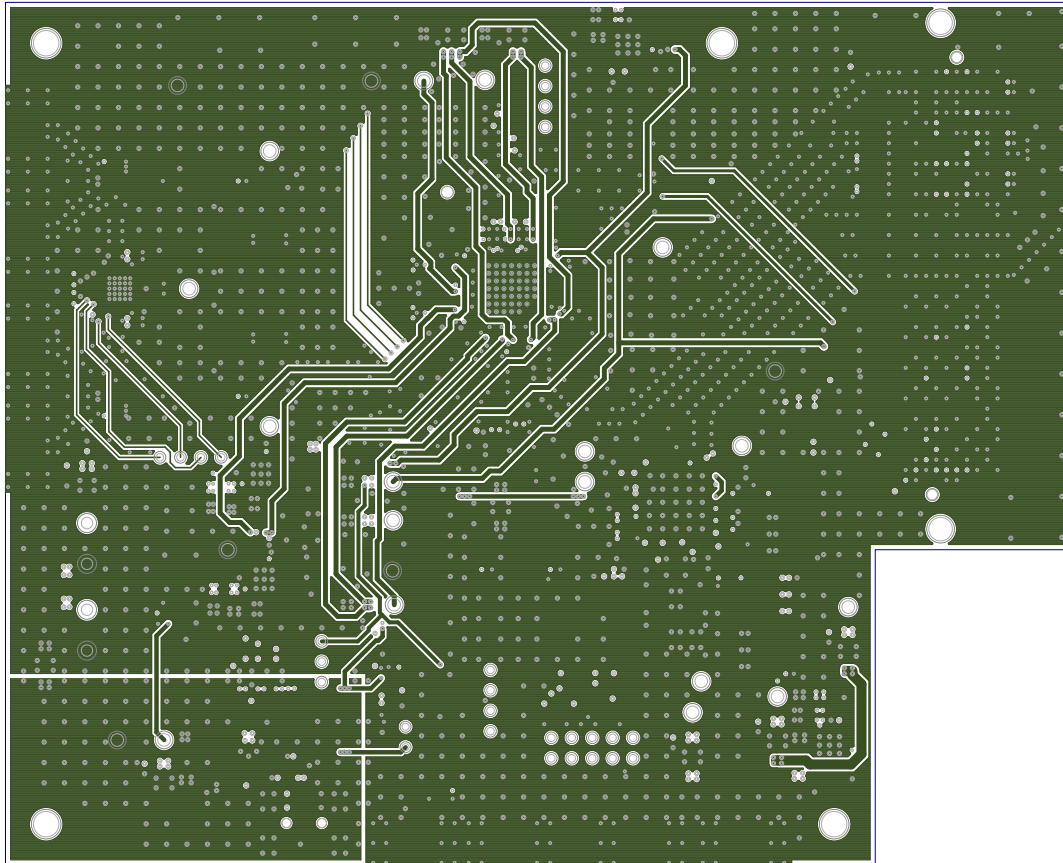
TEXAS INSTRUMENTS, INC.
 ADC16DX370/LM97937 EVM
 PCB REV A
 SILKSCREEN TOP SIDE



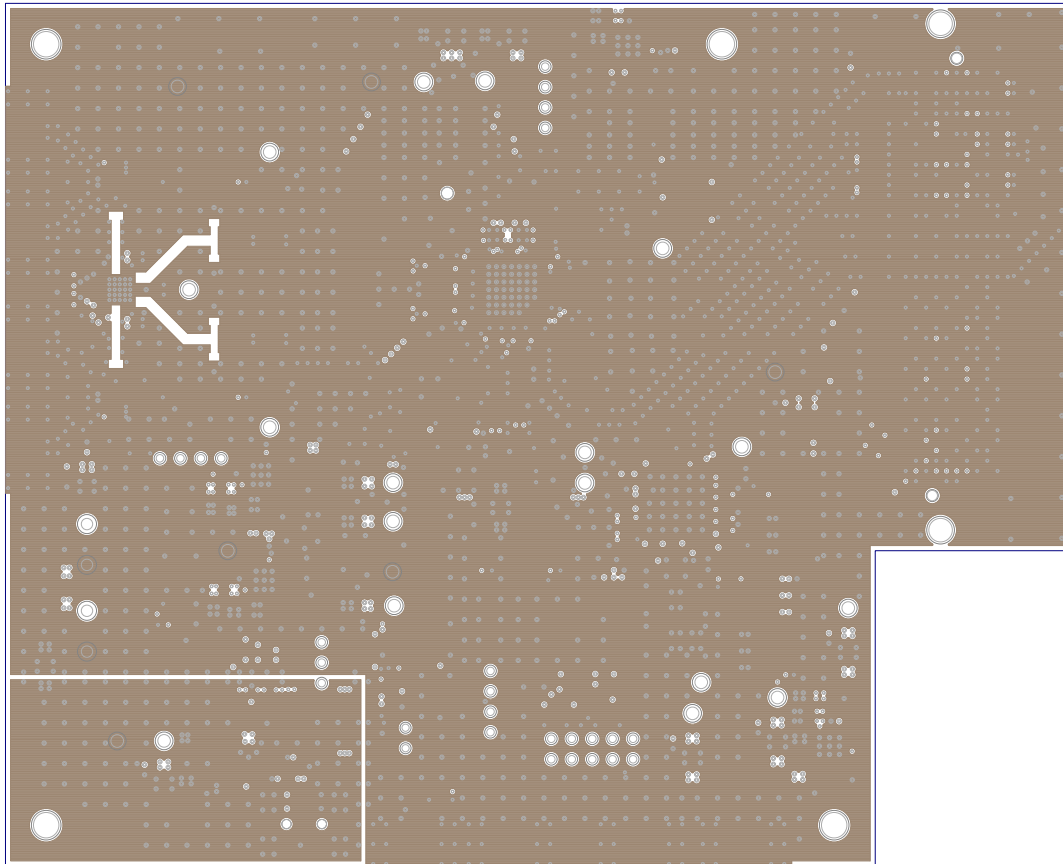
TEXAS INSTRUMENTS, INC.
ADC16DX370/LM97937 EVM
PCB REV A
LAYER 2- GROUND PLANE 1



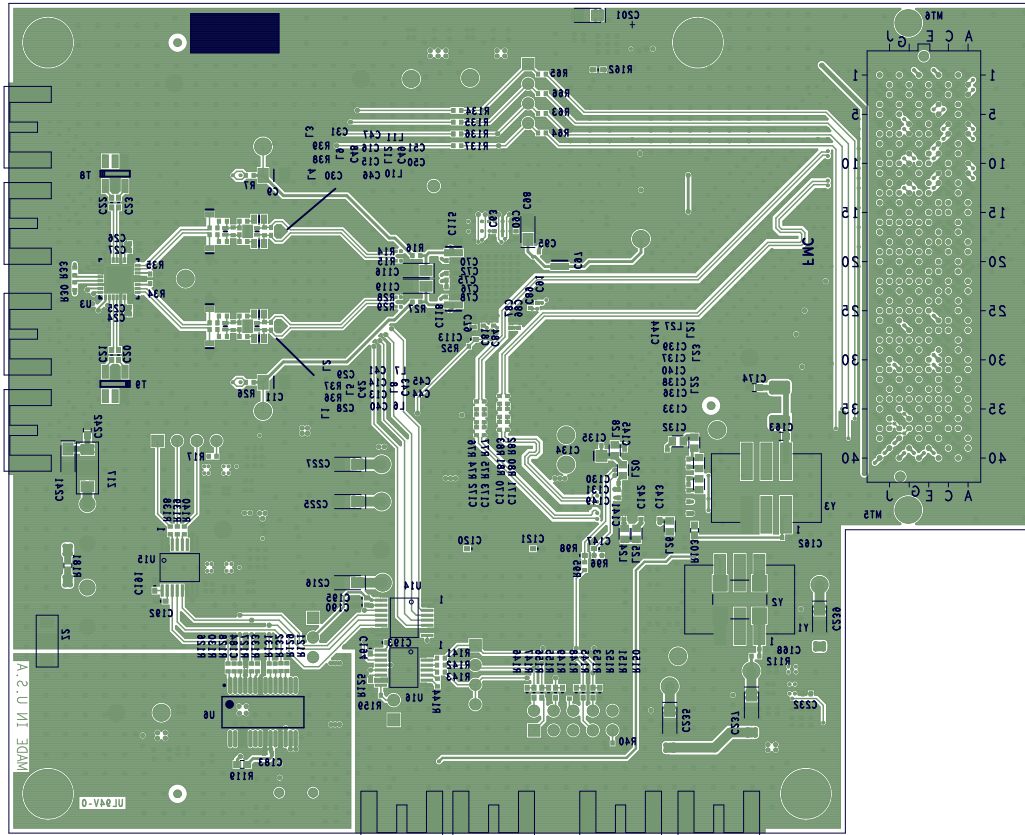
TEXAS INSTRUMENTS, INC.
ADC16DX370/LM97937 EVM
PCB REV A
LAYER 3- POWER PLANE



TEXAS INSTRUMENTS, INC.
ADC16DX370/LM97937 EVM
PCB REV A
LAYER 4- GROUND PLANE 2



TEXAS INSTRUMENTS, INC.
ADC16DX370/LM97937 EVM
PCB REV A
LAYER 5- GROUND PLANE 3



TEXAS INSTRUMENTS, INC.
 ADC16DX370/LM97937 EVM
 PCB REV A
 SILKSCREEN BOTTOM SIDE

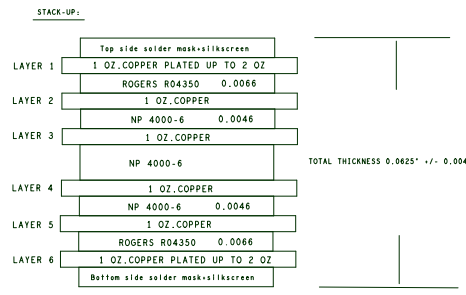
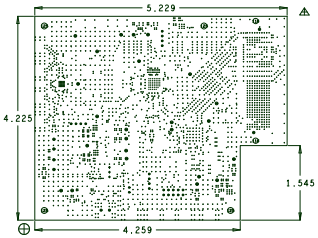
- UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.
- APPLICATION DESIGN, MANUFACTURING AND INSPECTION DOCUMENTS, IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES, IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD, IPC-A-6006 / ACCEPTABILITY OF PRINTED BOARDS.
 - HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE $\pm .003/- .010$.
 - REGISTRATION TOLERANCE: ARTWORK $\pm .002$, ALL HOLE CENTERS $\pm .005$ FROM DIMENSION DATUM.
 - MINIMUM COPPER WALL THICKNESS SHALL BE $.001$ INCH. FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
 - PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0. MATERIAL: MULTI-LAYER (SEE DETAIL 'A'). SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: $.062 \pm .010$.
 - MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
 - SMOBC/IMMERSTION GOLD: 3 - 8 μ IN OVER 100-200 μ IN NICKEL PLATING.
 - SOLDERMASK BOTH SIDES USING TATFO (OR EQUIVALENT) COLOR = RED (0.001 TO 002" THICK OVER METAL).
 - SILKSCREEN BOTH SIDES USING WHITE NP1 LEADFREE. REGISTRATION TOLERANCE TO BE $\pm .005$. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
 - P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
 - BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED $.007$ INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
 - BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

- ALL OUTER LAYERS USING A 12MIL TRACE WIDTH SHALL BE 50 OHMS SINGLE ENDED $\pm 10\%$.
- ALL INNER LAYERS USING A 12MIL TRACE WIDTH SHALL BE 50 OHMS SINGLE ENDED $\pm 10\%$.
- ALL OUTER LAYERS USING A 6MIL TRACE WIDTH AND 6MIL SPACING SHALL BE 100 OHMS DIFFERENTIAL $\pm 10\%$.
- ALL INNER LAYERS USING A 6MIL TRACE WIDTH AND 6MIL SPACING SHALL BE 100 OHMS DIFFERENTIAL $\pm 10\%$.
- MINIMUM COPPER CONDUCTOR WIDTH IS: 5MIL.
- MINIMUM COPPER CONDUCTOR SPACING IS: 4.5MIL.
- ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.
- PWB MUST BE ROHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY. MAX REFLOW OF 260 DEGREES C (6 PASSES).
- ALL THROUGH VIAS TO BE PLUGGED WITH NON-CONDUCTIVE EPOXY MATERIAL. PLUGGED VIAS TO BE PLATED AFTER PLUGGING TO PRESENT FLAT SURFACE TO DEVICE. NO POTHOLEES.

REVISIONS			
ZONE	LTR	DESCRIPTION	DATE APPROVED

D
C
B
A

D
C
B
A



DRILL CHART, TOP TO BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
-	8.0	PLATED	46
-	12.0	PLATED	2458
-	12.0	PLATED	17
•	36.0	PLATED	2
•	37.0	PLATED	22
•	38.0	PLATED	3
•	56.0	PLATED	4
•	63.0	PLATED	23
⊙	116.0	PLATED	2
⊙	125.0	PLATED	4
•	46.0	NON-PLATED	2
•	51.0	NON-PLATED	2
•	59.84	NON-PLATED	1

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES $\pm .01$ $\pm .005$ $\pm .01$	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING	
MATERIAL	SEE NOTE 5	DRAWN	L. NGUYEN	01-16-14
FINISH	SEE NOTE 7, 8, 9	ENG	J. CANNES	01-16-14
DO NOT SCALE DRAWING		SIZE	B	CODE IDENT NO. DRAWING NO.
		SCALE	NONE	SHEET 1 OF 1

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